Michigan State University Engineering and Digital Innovation Center

21st Century Facilities for a 21st Century Workforce

- Michigan needs a trained workforce in essential disciplines to ensure we are a leading manufacturing hub in many industries.
- This request is to meet industry needs and student demands to advance research opportunities.
- The State of Michigan needs a facility to maintain and develop excellence in material science, ultrafast science, quantum computing, heterogeneous micro-electronic technologies and advance manufacturing.
- Innovations coming out of the intersection of digital science and material science will be commercialized (licensed IP or startups in Michigan) to support chip manufacturing, electric vehicles, and alternative energy.
- The Bureau of Labor Statistics forecasts 667,600 new jobs in computer science related fields, with a median income of $97,500 - we can help Michigan compete for these jobs.
- The Engineering and Digital Innovation Center is a $250m, 270,000 square foot facility focused on education and research at the convergence of the digital and physical technologies.
- Providing teaching, learning, and research space for:
  - 50 principal investigators and research teams
  - 1,500 new engineering students
  - Nearly 60% of MSU engineering students remain in Michigan upon graduation.
- MSU is seeking a $150m commitment from our state partners to support this Engineering and Digital Innovation Center.

**At a Glance:**
- Estimated cost: Approximately $250m
- Approximate size: 270K sq.ft.
  - Digital experience: 140K sq.ft.
  - Materials science: 130K sq.ft.
- 50 principal investigators and research teams
- Increased enrollment of new undergraduate and graduate students

**EDIC Location**

**Aligns modern building space functionality and infrastructure with new capacity for innovation.**

**Supports synergies between researchers and students, enhancing potential for discovery.**

**Increases the potential to attract significant federal funding in high-demand research areas.**